

Title (en)
METHOD FOR INTERCONNECTING ACTIVE AND PASSIVE COMPONENTS, AND A RESULTING THIN HETEROGENEOUS COMPONENT

Title (de)
METHODE ZUM VERBINDEN AKTIVER UND PASSIVER BAUTEILE UND DARAUS ENTSTANDENES HETEROGENES BAUTEIL GERINGER DICKE

Title (fr)
PROCEDE D INTERCONNEXION DE COMPOSANTS ACTIF ET PASSIF ET COMPOSANT HETEROGENE A FAIBLE EPAISSEUR EN RESULTANT

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Application
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Abstract (en)
[origin: WO2005004237A1] The invention relates to a method for interconnecting thin active and passive composites having two or three dimensions, and to the resulting thin heterogeneous components. According to the invention, the invention involves: the positioning and fixing (11) of at least one active component and one passive component to a supporting surface (23), the contacts being in contact with the support; the deposition (12) of a polymer layer (24) onto the assembly consisting of the support and of these components; the withdrawal (14) of the support; the redistribution of the contacts between the composites and/or toward the periphery by means of metallic conductors (26) arranged according to a predetermined configuration, whereby making it possible to obtain a reconstituted heterogeneous structure; heterogeneous thinning (16) of this structure by non-selective surface finishing of the polymer coating and of at least one passive component (22).

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